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wafer-scale micro-transfer

printing

Project INSPIRE leverages microtransfer printing technology to realize heterogeneous InP/SiN photonic integrated circuits, combining the best of both the indium phosphide and silicon nitride photonics technology. InP devices will be printed on SiN, using new, innovative hybrid building blocks and printing methods. The large-scale manufacturing of transfer-printed assemblies is extended to PIC technology by enabling relaxed alignment tolerances to the micron-scale and enhancing the capabilities for high volume printing.

INSPIRE creates manufacturable, crossplatform building blocks which leverage the powerful combination of European pilot line technology and proven printing methods. The innovations proposed will deliver a 200mm photonic integration platform with high-performance SiN and InP components.







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